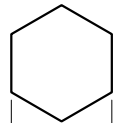


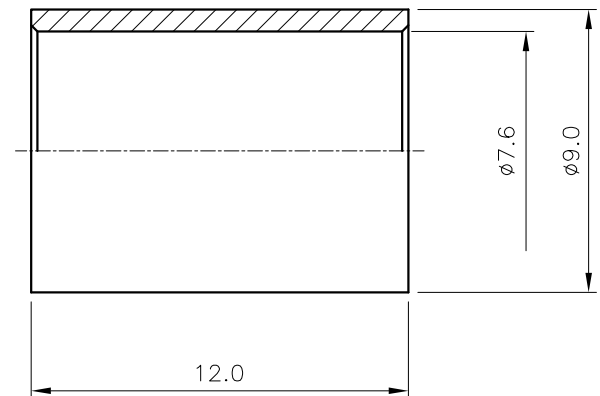
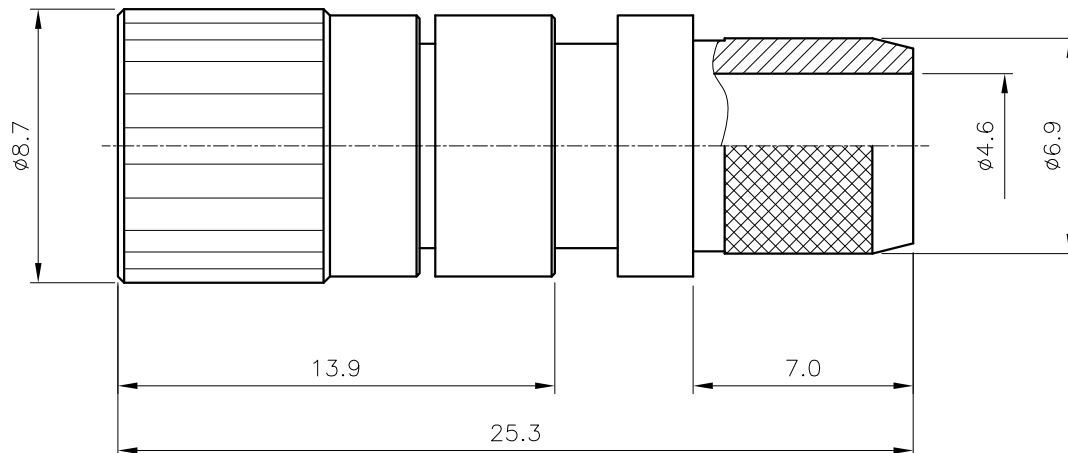
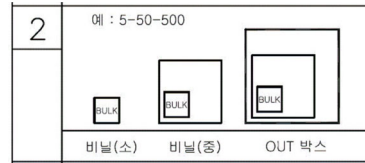
CABLE 탈피도



CRIMP SIZE

■ 포장 사양

1. 자크봉지 ■ 가로-세로mm 150-200 CN03785-7/3 100EA씩
2. 자크봉지 ■ 가로-세로mm 080-130 DFE00215-5/3 100EA씩
3. 자크봉지 ■ 가로-세로mm 055-080 DCT03953-5/1 100EA씩



ELECTRICAL DATA :

1. IMPEDANCE : 50ohm
2. FREQUENCY RANGE : DC~1GHz
3. VSWR (Max) : 1.25
4. INSULATION RESISTANCE : $\geq 200M\Omega$
5. CENTER CONTACT RESISTANCE : $\leq 10m\Omega$
6. OUTER CONTACT RESISTANCE : $\leq 3m\Omega$
7. TEST VOLTAGE : 750 V RMS
8. WORKING VOLTAGE : 250 V RMS

MECHANICAL DATA :

1. ENGAGEMENT FORCE : $\leq 10N$
2. DISENGAGEMENT FORCE : $\leq 10N$
3. DURABILITY : ≥ 500

ENVIRONMENTAL DATA :

1. TEMPERATURE RANGE : $-55^{\circ}C \sim +125^{\circ}C$
2. MOISTURE RESISTANCE : MIL-STD-202, METHOD 106

REVISION

REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	S.Y.EUN	I.C.KIM	2020.02.25.
1	JACK 두께변경 부러짐 개선	S.Y.EUN	I.C.KIM	2020.07.16.
2	JACK + BODY 억지끼움부 개선	S.H.KIM		2023.08.09.
3	조립성 감안 CAP,BODY 치수 조정	S.H.KIM		2024.01.29.

7	SPRING	1	SUS303	Passivated	DSR00002-5/1
6	CAP	1	MBsBD C3604BD-F	Gold Plate	DCU02298-5/1
5	JACK	1	BeCu C17300	Gold Plate	DJA00064-5/3 DJA00064-5/2
4	FERRULE	1	MBsBD C3604BD-F	Nickel Plate	DFE00215-5/3
3	INSULATOR	1	TEFLON		DIN03000-N/1
2	CONTACT	1	MBsBD C3604BD-F	Gold Plate	DCT03953-5/1
1	BODY	1	MBsBD C3604BD-F	Nickel Plate	DBD04408-5/4 DBD04408-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.2	DATE 2024. 01. 29.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017		
	Angle ±1°	APPROVED BY					
	MATERIAL _____		CHECKED BY			TITLE 1.0/2.3 DIN75 CABLE PS RG6 SCREW	
FINISH _____		DRAWN BY S.H.KIM					
		SCALE 4/1	UNIT mm		A4	DWG NO. CN03785-7/3	
						REVISION 3	SHEET 1 of 1